DSA7102

Silicon PNP epitaxial planar type

For low frequency amplification Complementary to DSC7102

■ Features

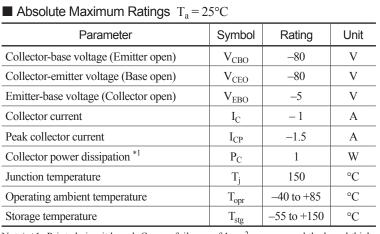
- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 4D

Packaging

 $DSA7102 \times 0L \quad Embossed \ type \ (Thermo-compression \ sealing): 1000 \ pcs \ / \ reel \ (standard)$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	-80	V
Collector-emitter voltage (Base open)	V _{CEO}	-80	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I _C -1		A
Peak collector current	I _{CP}	-1.5	A
Collector power dissipation *1	P _C	1	W
Junction temperature	T _j	150	°C
Operating ambient temperature	T _{opr}	-40 to +85	°C
Storage temperature	T _{stg}	-55 to +150	°C



Note) *1: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion Absolute maximum rating without heat sink for P_C is 0.5 W

Unit: mm 4.5 1.6 0.41 0.4 0.5 1.5 3.0 1: Base 2: Collector 3: Emitter MiniP3-F2-B Panasonic **JEITA** SC-62 Code TO-243

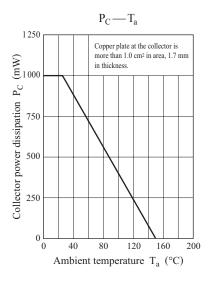
■ Electrical Characteristics $T_a = 25$ °C±3°C

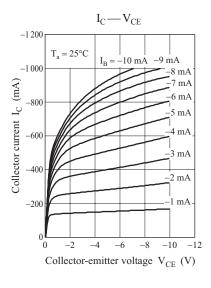
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \mu\text{A}, I_{\rm E} = 0$	-80			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-80			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \mu\text{A}, I_{\rm C} = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -40 \text{ V}, I_E = 0$			-0.1	μА
Forward current transfer ratio *1	h _{FE1} *2	$V_{CE} = -2 \text{ V}, I_{C} = -100 \text{ mA}$	120		340	
	h _{FE2}	$V_{CE} = -2 \text{ V}, I_{C} = -500 \text{ mA}$	60			_
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		-0.2	-0.3	V
Base-emitter saturation voltage *1	V _{BE(sat)}	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$		-0.95	-1.2	V
Transition frequency	f_T	$V_{CE} = -10 \text{ V}, I_{C} = -50 \text{ mA}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		12	30	pF

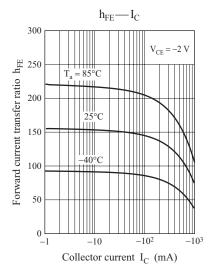
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

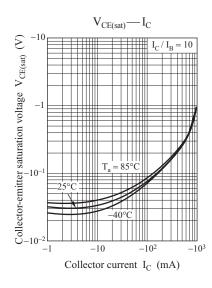
- 2. *1: Pulse measurement
 - *2: Rank classification

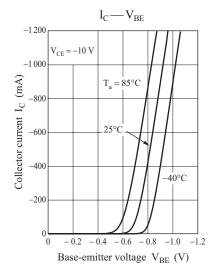
Code	R	S	
Rank	R	S	
h_{FE1}	120 to 240	170 to 340	
Marking Symbol	4DR	4DS	

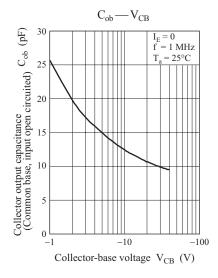


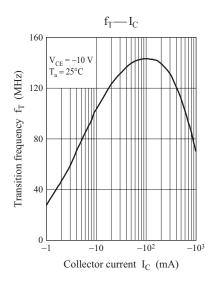








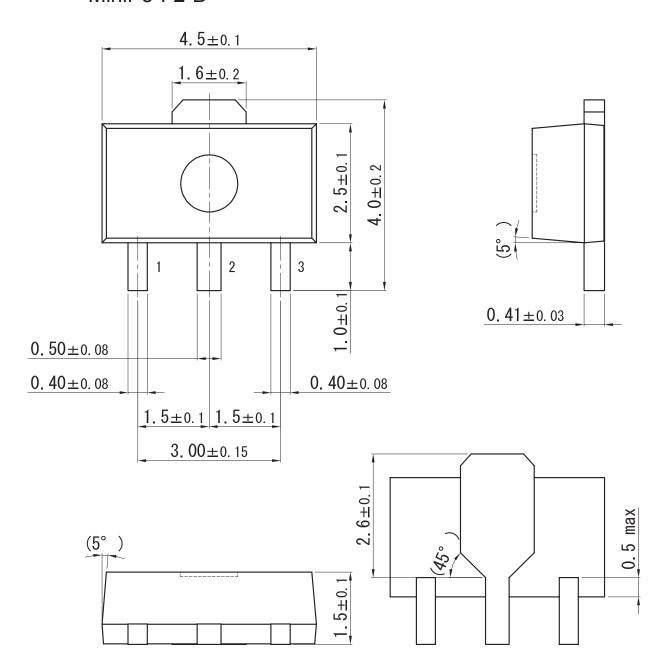




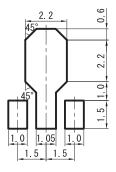
Ver. EED 2

MiniP3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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